

### IN THE CLAIMS

Please amend the claims in accordance with the following rewritten claims in clean form. Applicant includes herewith an Attachment for Claim Amendments showing a marked up version of each amended claim.

*BB* 3. (Amended) A semiconductor device connecting structure as defined in claim 1, characterized in that said space further comprises a plurality of spaces placed closely to each other.

*BB* 4. (Amended) A semiconductor device connecting structure as defined in claim 1, characterized in that said bonding material is an anisotropic conductive film including conductive particles dispersed into a resin film.

*BB* 5. (Amended) A semiconductor device connecting structure as defined in claim 1, characterized in that the percentage of said space within said bonding material is 5% to 70%.

6. (Amended) A semiconductor device connecting structure as defined in claim 5, characterized in that the percentage of said space within said bonding material is 10% to 30%.

*BB* 13. (Amended) A liquid crystal display unit as defined in claim 11, characterized in that said space further comprises a plurality of spaces placed closely to each other.

*BB* 14. (Amended) A liquid crystal display unit as defined in claim 11, characterized in that said bonding material is an anisotropic conductive film including conductive particles dispersed into a resin film.